

TG-NSP25

Non-Silicone Thermal Putty

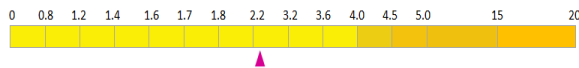


Features

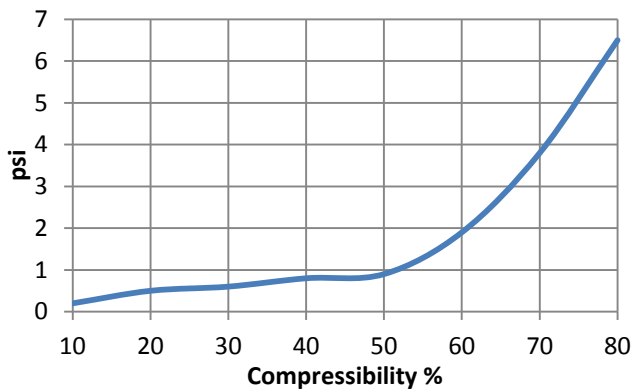
- TG-NSP25 is a silicone-free type spacer with 2.5 W/m.K
- Have enough compressibility
- It has very low thermal resistance
- It is the best for north bridge IC

Properties

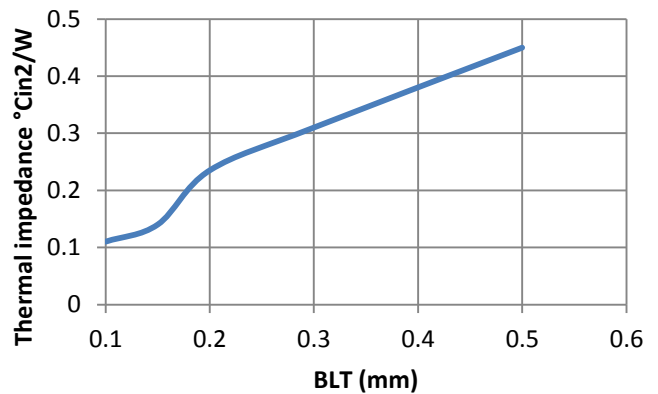
Thermal Conductivity: 2.5 W/m.K



Have enough compressibility



Very low thermal resistance



Reliability

Thermal Impedance	Initial	250 Hr	500 Hr	1000 Hr
80°C Aging	0.124	0.125	0.127	0.126
150°C Aging	0.128	0.129	0.129	0.13
85°C/85% RH	0.126	0.128	0.129	0.131

Physical Properties	TG-NSP25	Unit	Tolerance	Test Method
Color	Gray	-	-	Visual
Solid Content	100	%	-	-
Viscosity 0.5rpm	5000	Pas	-	Brookfield
Density	2.6	g/cm3	-	ASTM D792
Thermal Conductivity	2.5	W/m.K	±0.25	ASTM D5470
Low MW Siloxane (D4-10)	0	ppm	-	GC/MS
TML	0.2	%	-	ASTM E595
CVCM	0.1	%	-	ASTM E595
Volume Resistivity	10 ¹⁴	Ohm-cm	-	ASTM D257
Working Temp.	-50 to 150	°C	-	-

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Thermal Interface Materials: Thermal Pad, Thermal Tape, Thermal Grease, Ceramic Heat Spreader

